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(54) **METHOD FOR CALCULATING THROUGHPUT IN SEMICONDUCTOR MANUFACTURING APPARATUS, SEMICONDUCTOR MANUFACTURING APPARATUS, AND COMPUTER PROGRAM PRODUCT**

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(57) **ABSTRACT**

An object is to obtain a throughput of a semiconductor manufacturing apparatus precisely. A method for calculating a throughput in a semiconductor manufacturing apparatus, which comprises plural units, is provided, and the method comprises steps for: obtaining a process parameter relating to processing of a substrate in the semiconductor manufacturing apparatus; obtaining, from a memory, maintenance information with respect to each unit in the plural units, wherein the maintenance information comprises timing of maintenance of each unit in the plural units and the length of time required for the maintenance, wherein the maintenance is that planned to be performed in a period that ends when processing of the substrate in the semiconductor manufacturing apparatus is completed; and calculating a throughput of the semiconductor manufacturing apparatus, based on the process parameter and the maintenance information.